

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.



C Sun Mfg Ltd.

QIC CEO Week 2025.4.15



Business Philosophy- ALL WIN



G2C+

合力共創 同行致遠

Well-intentioned motives
lead careers to success

---From 『Heart』 Inamori Kazuo

The Alliance Members: 1700+



R&D personnel: 560+

R&D personnel account for 32.5%



Since 1966

Since 1978

Since 1978

***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

Foundry 2.0

Downstream
Integration

Info
cWoS
Solc

Advanced Packaging

OSAT
Upstream
Development

MEM

FOCOS

SiP

PLP

FC → WLCSP → 2.5D

c sun Bonder
Lamination
Peeling

GPM AOI
Metrology
Grinding
Polishing

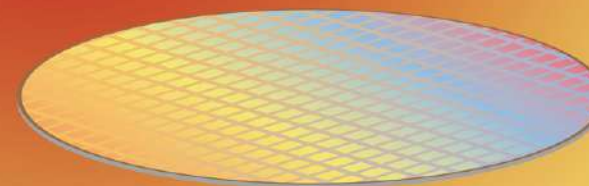
GMM Die Attach
Chip Storter
Auto Jid Saw

Advance Packaging

IC Substrate 、 HBM Packaging 、 2.5/3DIC



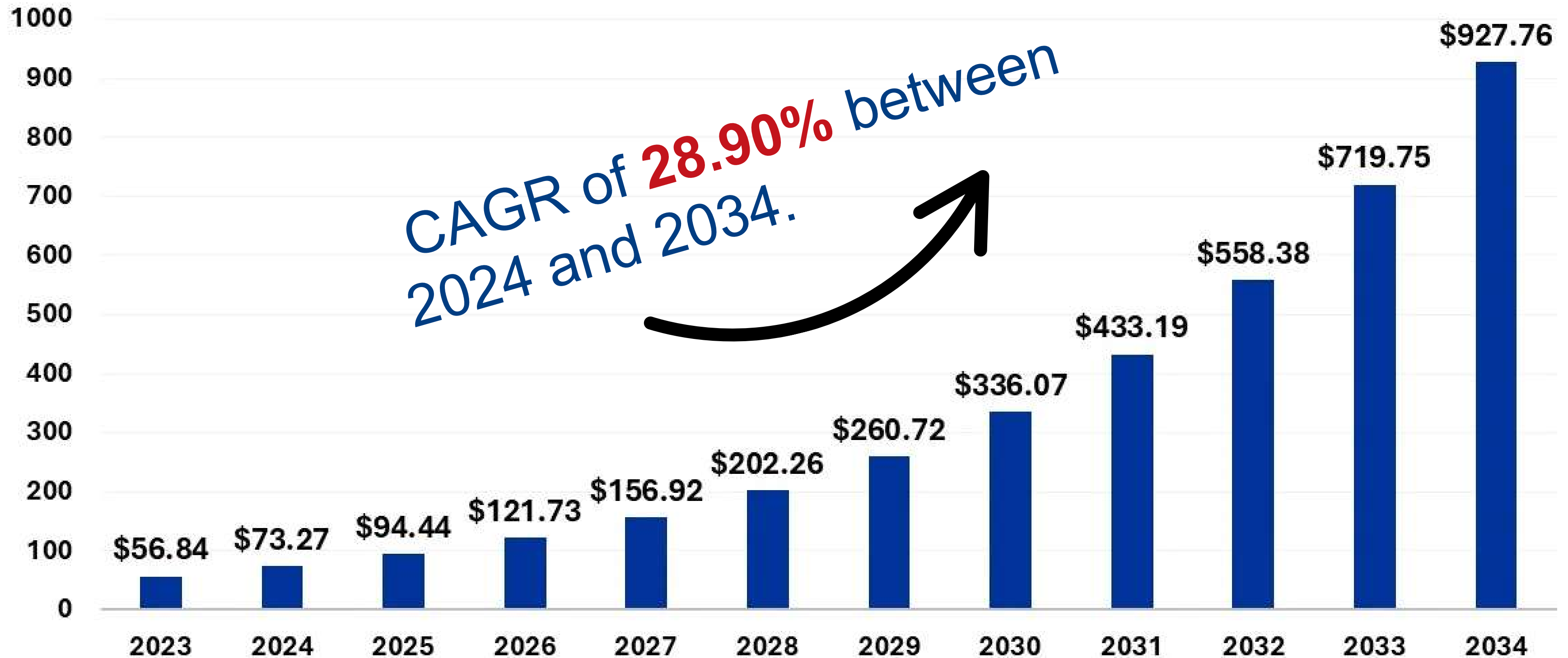
GT2C+
T STRATEGY ALLIANCE



c sun GPM

Foundry
Reclaim wafer

Artificial Intelligence (AI) Chip Market Size 2023 to 2034 (USD Billion)



Taiwan's West Golden Corridor: **AI Chips**

The Shining Diamond Chain of Advanced Packaging Processes

Taiwan's Market Share in
Packaging and Testing by Value

58.6 %

Taiwan's Market Share in
Wafer Manufacturing by Value

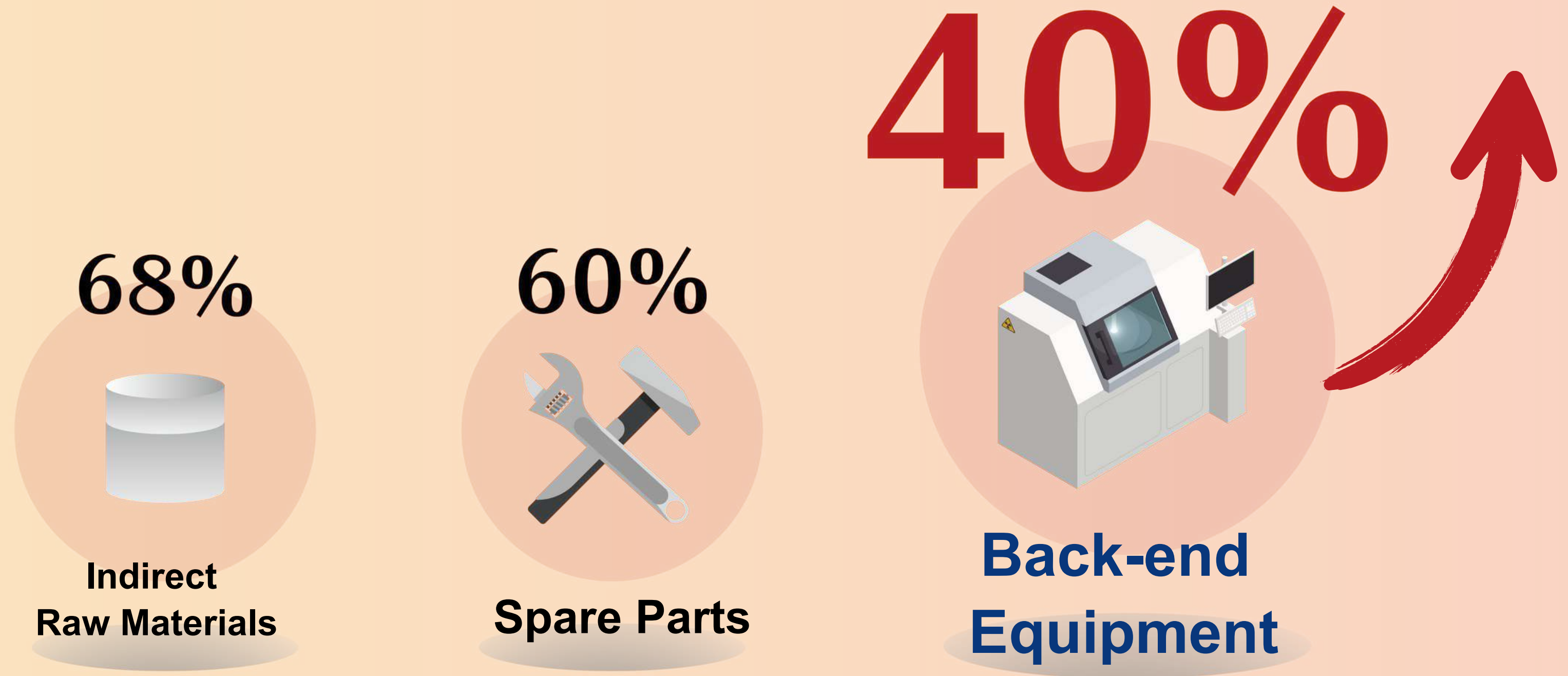
76.8 %



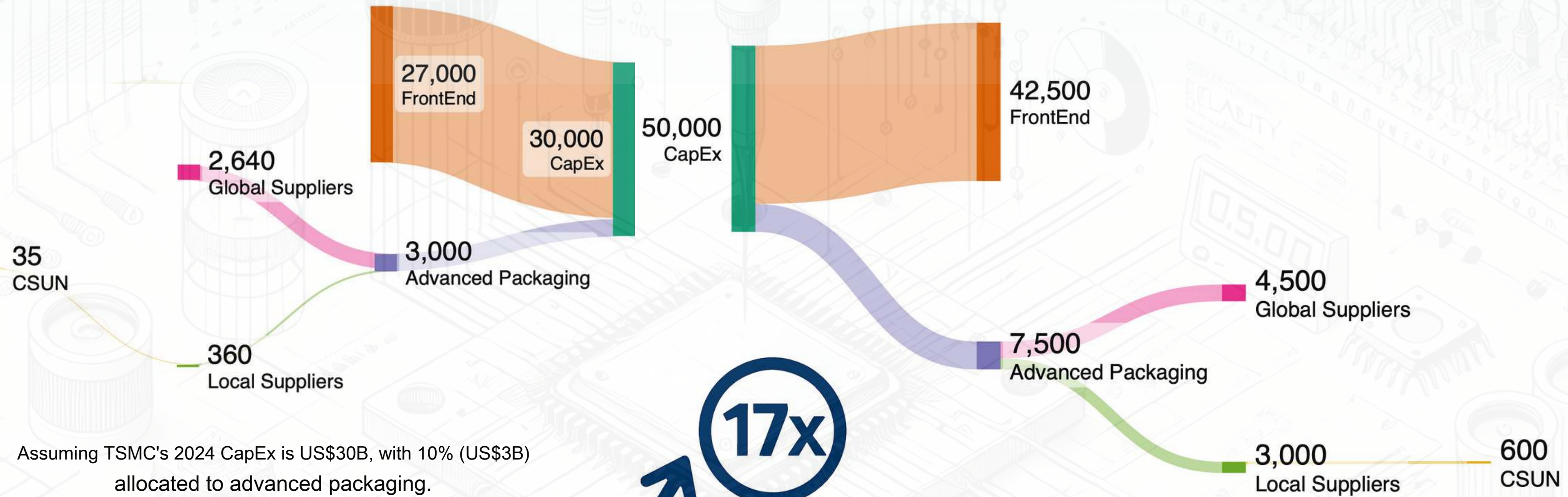
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TSMC is committed to increase local procurement

Vision for 2030

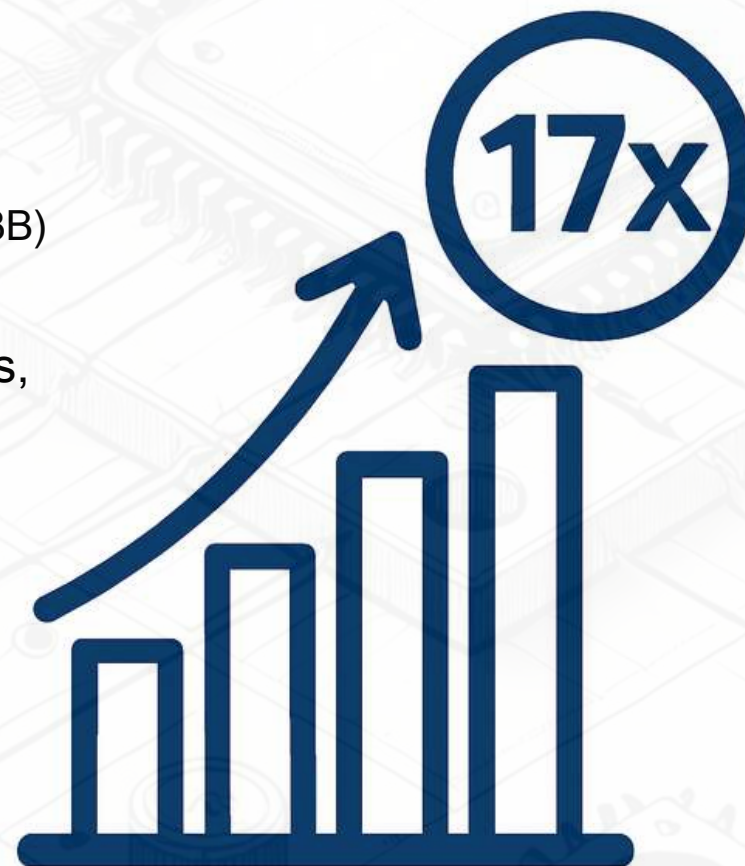


US\$M



Assuming TSMC's 2024 CapEx is US\$30B, with 10% (US\$3B) allocated to advanced packaging.

Of that, 12% (US\$360M) goes to local tool suppliers, CSUN accounts for US\$35M.



Company Introduction



2023、2024
TSMC Award

Employee and Family
Shareholding >40%

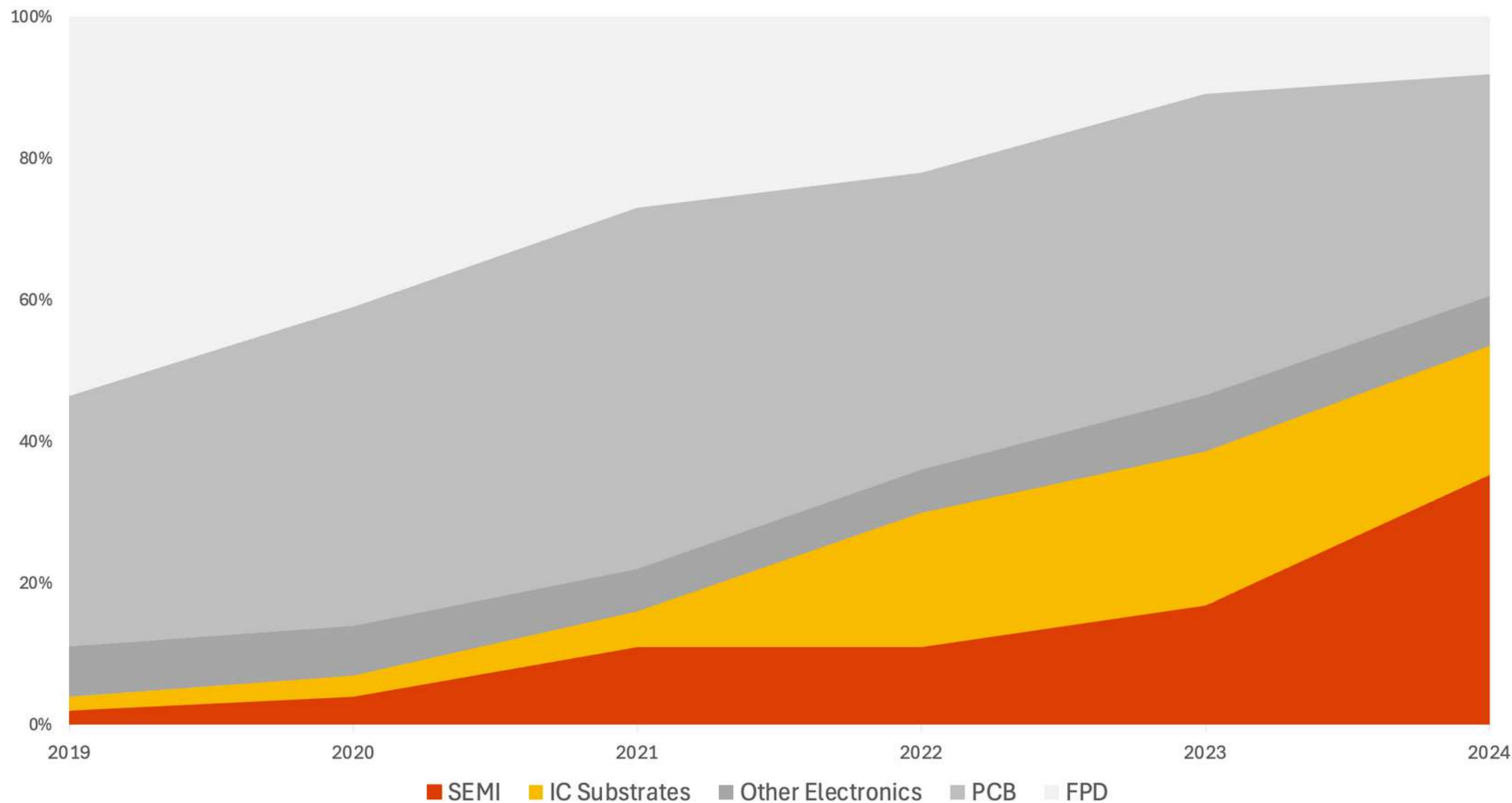


Establishment: 1966.9.28
Capital: NT\$1.56 billion
Chairman: Morrison Liang
President: Frank Liang

Financial Review

NT\$M	25Q1	2024	2023	YoY
Net revenue	1,309	4,818	3,626	32.9%
Gross Margin%		41.2%	41.5%	-0.3ppts
Operating Expense		-1,347	-1,104	22%
OPEX%		28.0%	30.4%	-2.4ppts
Operating Margin%		13.2%	11.1%	+2.1ppts
Non-Operating items		344	181	89%
Net income contributable to Share holders of the parent company		719.16	486,324	48%
Net Profit Margin%		14.9%	13.4%	+1.5ppts
EPS(NT\$D)		4.8	3.12	54%
ROE%		16.6%	14.1%	-

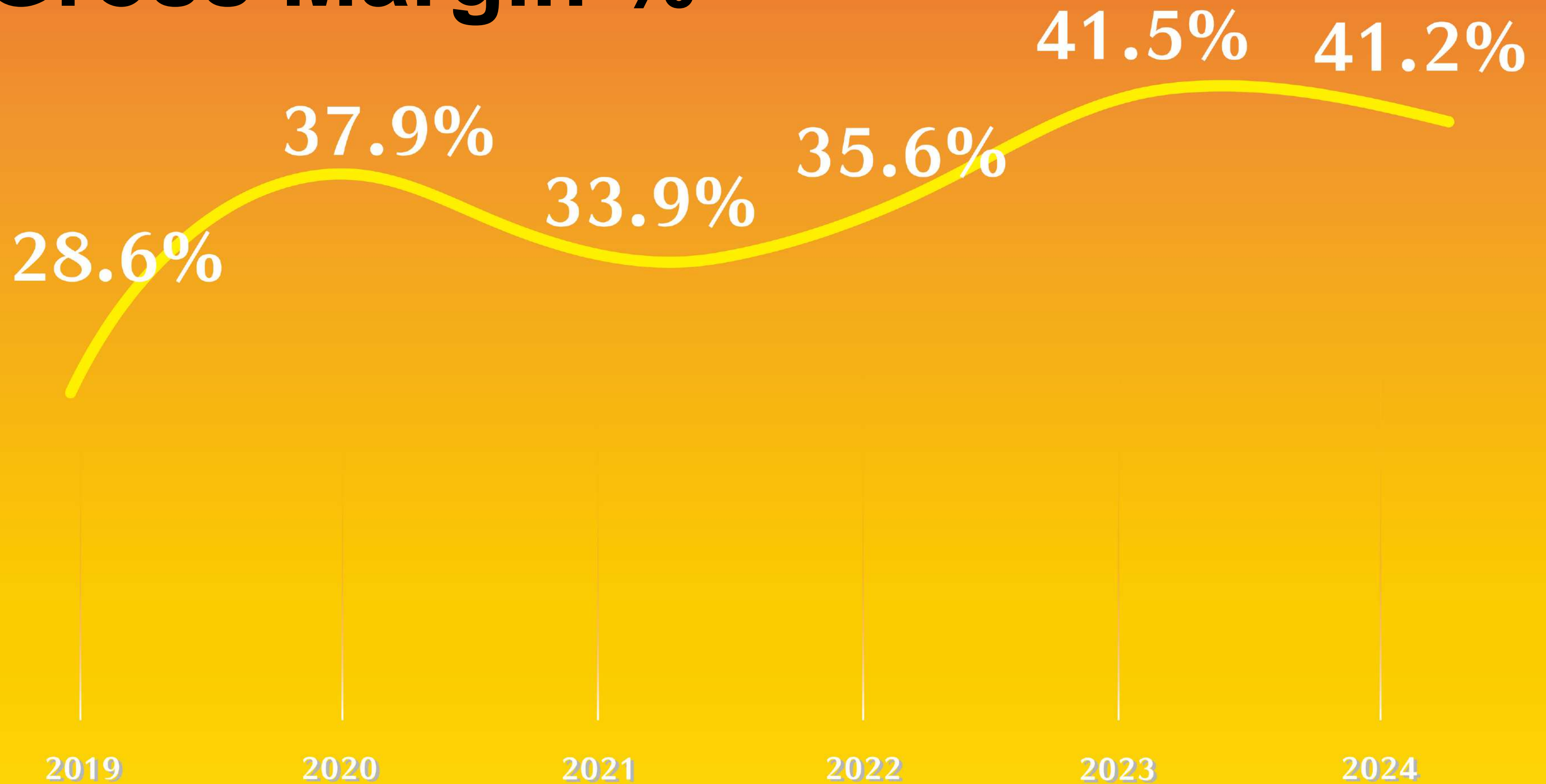
Revenue Composition



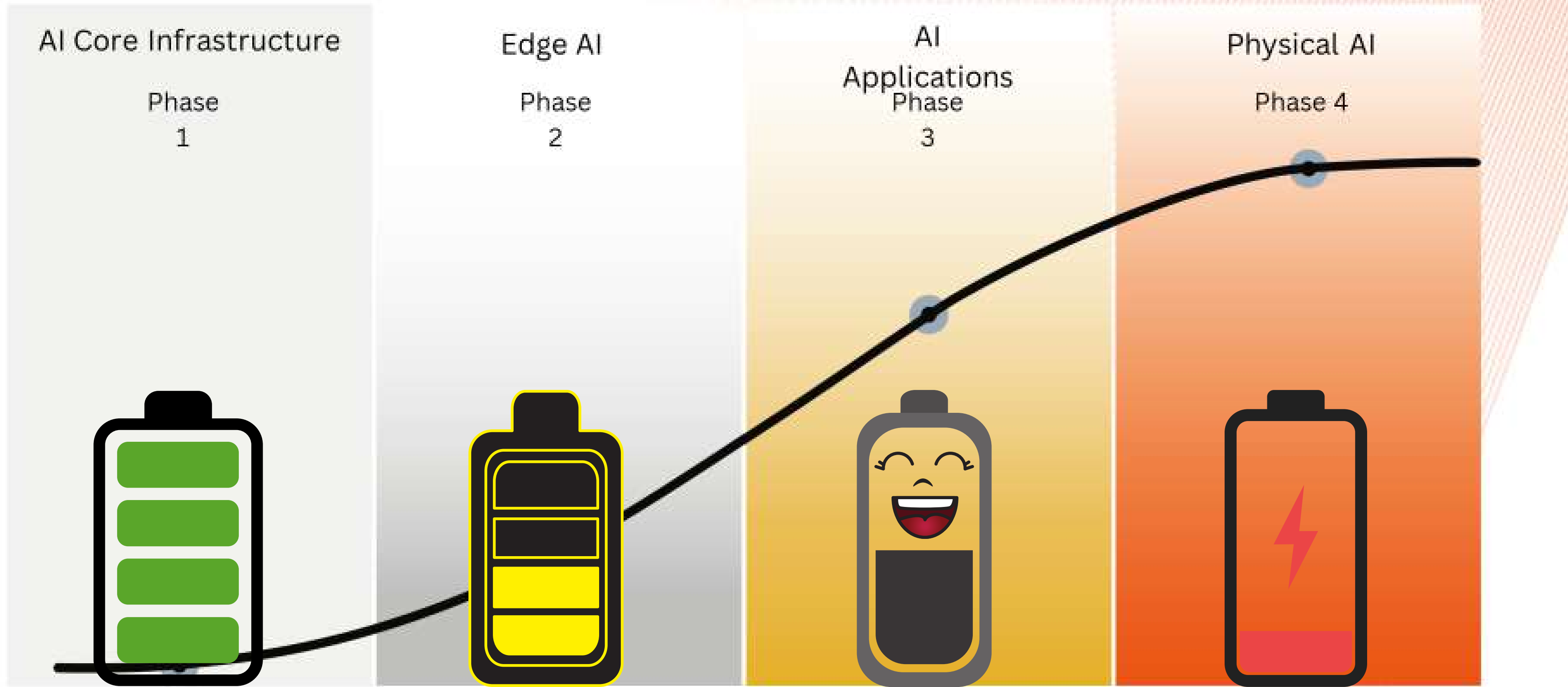
SEMI~35%



Gross Margin %



Coatue Framework for AI S-Curve





AI 聚焦

HBM

oS

LPO

Assembly

IC Substrate

CoW

SoC/SolC

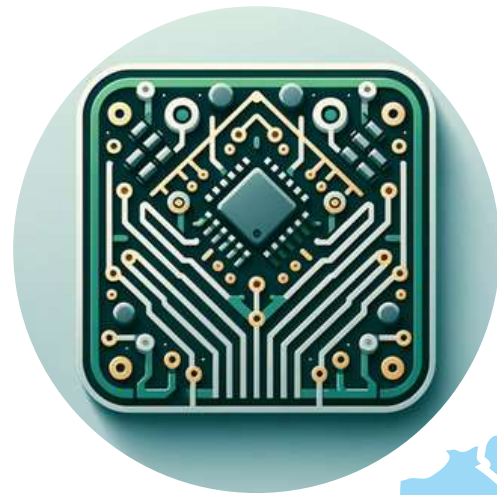
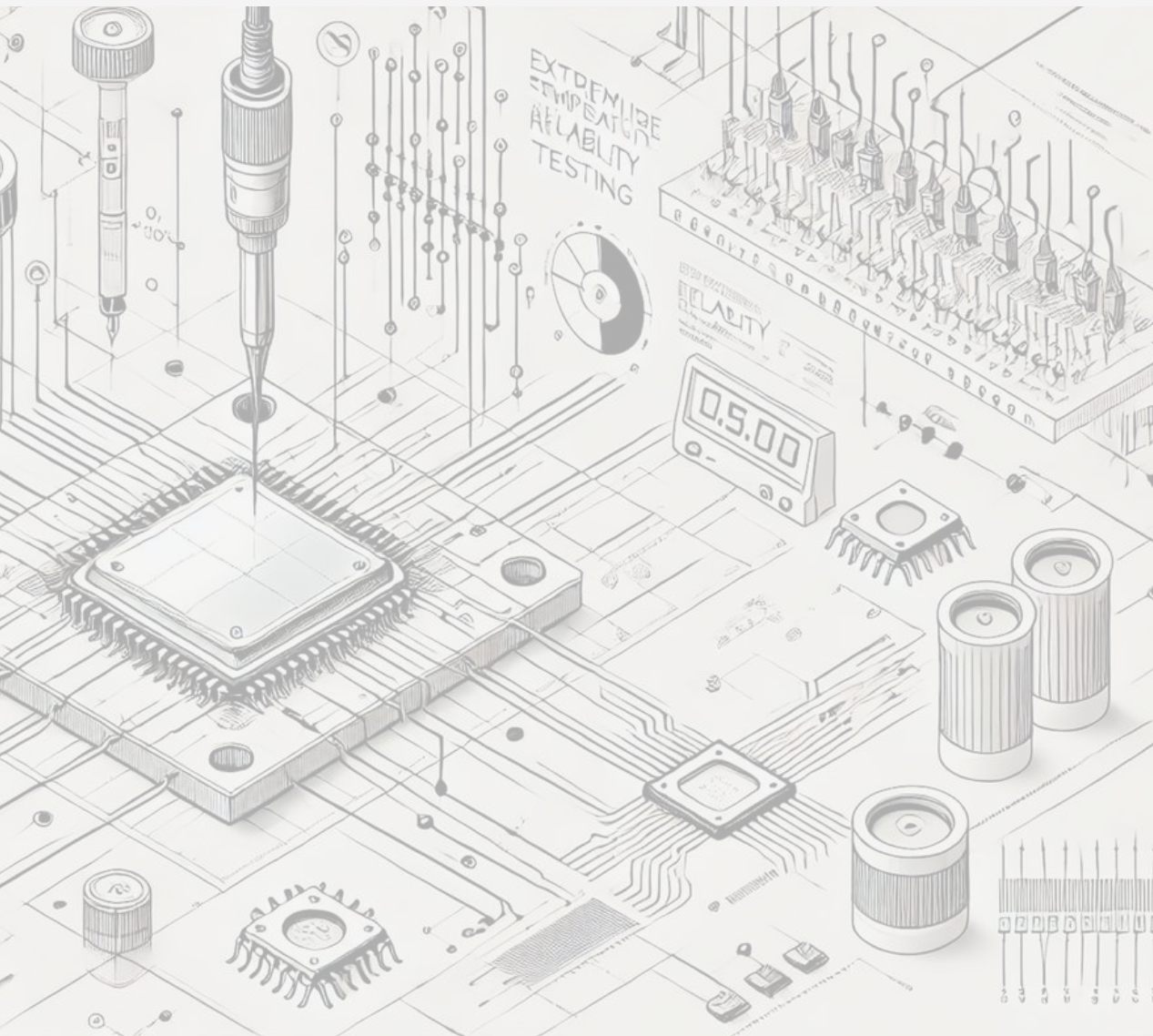
CPO

Test

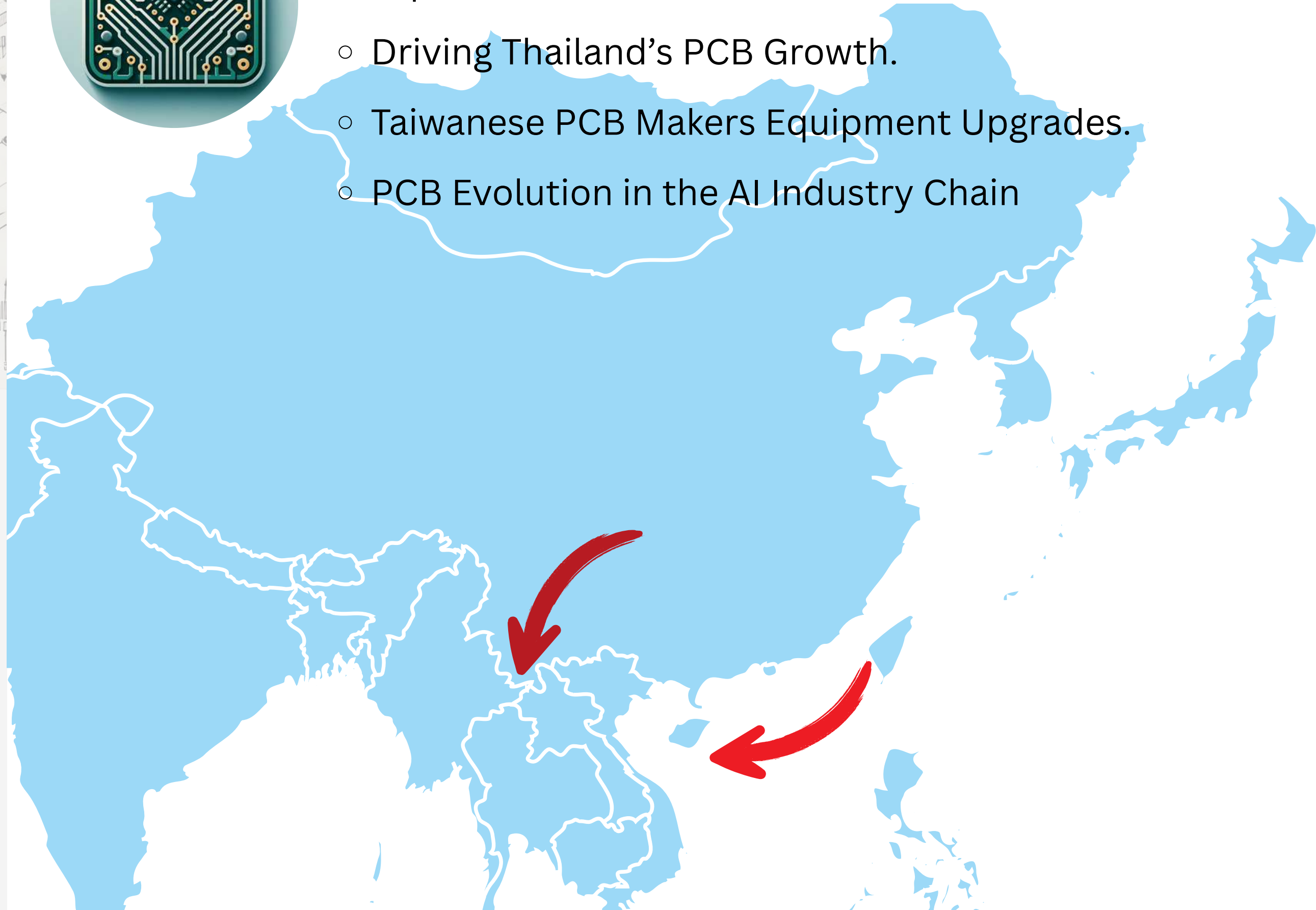
Mother Board

2024

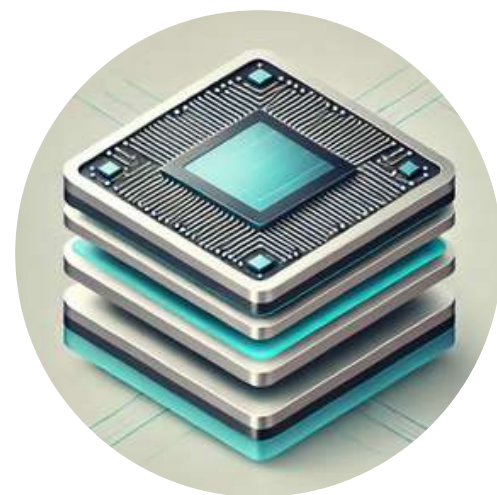
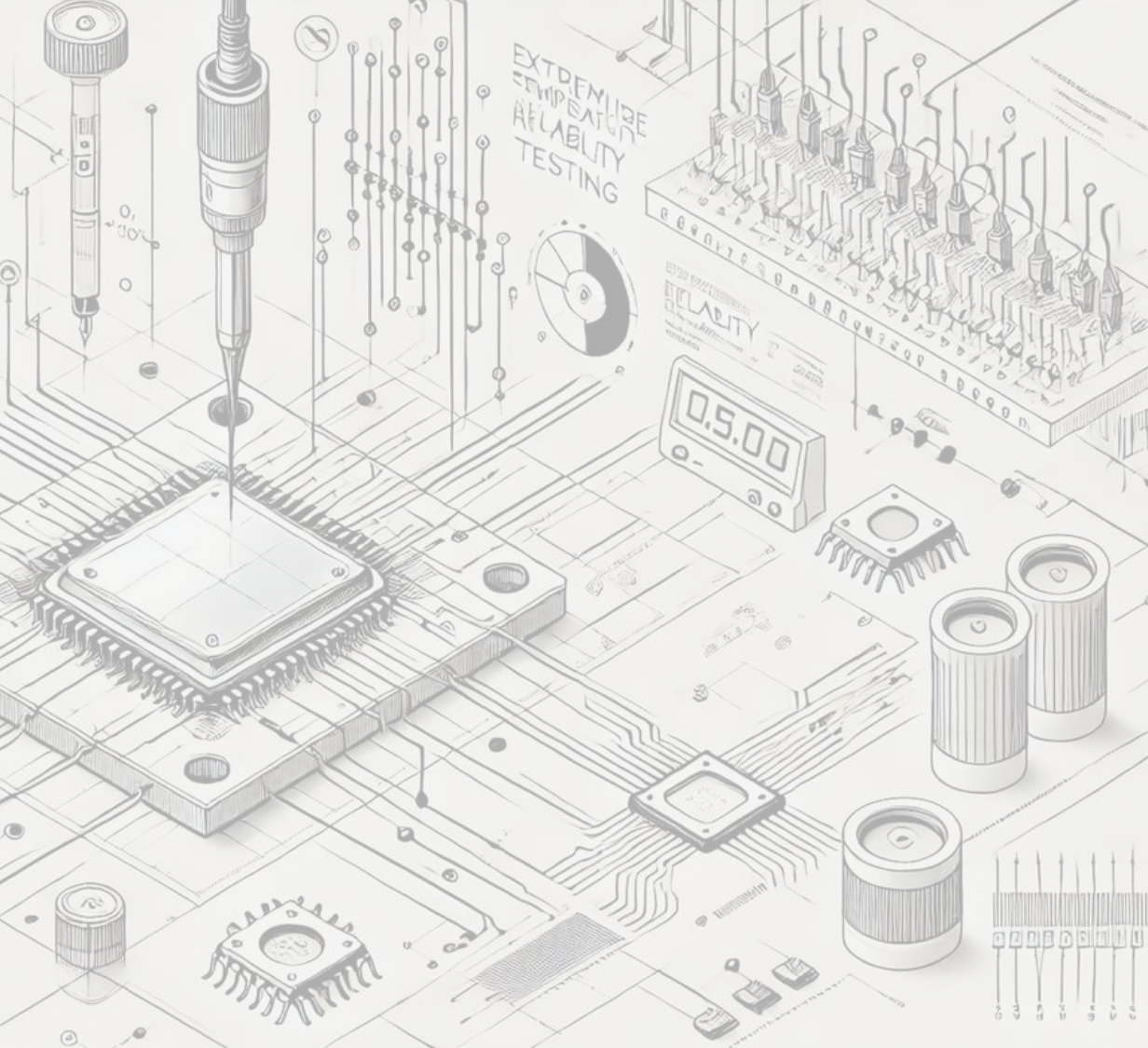
>50%



- Server and HDI Demand Rebounds
- Expansion in Southeast Asia
- Driving Thailand's PCB Growth.
- Taiwanese PCB Makers Equipment Upgrades.
- PCB Evolution in the AI Industry Chain



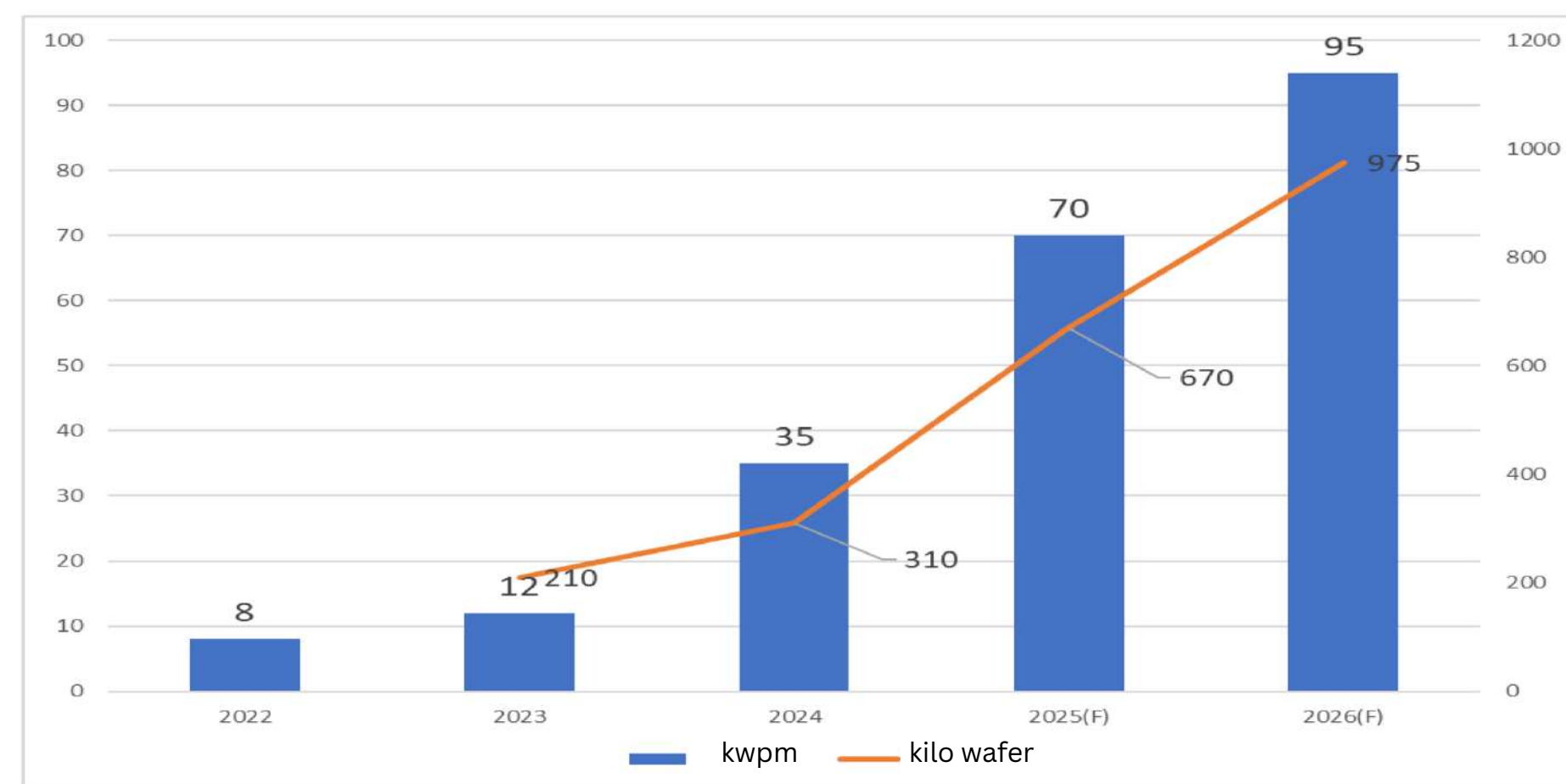
The Evolving Landscape of the PCB Industry



Dynamics of CoWoS Demand and Production Capacity

- DeepSeek Phenomenon.
- CoWoS Process Remains Primary Process for AI Chips.
- **Clients' Capacity Expansion Drives Equipment Demand**
- Additional Process Stations to Boost Equipment Penetration.

Prospects for
Equipment in Leading
Customers' Advanced
Packaging Processes

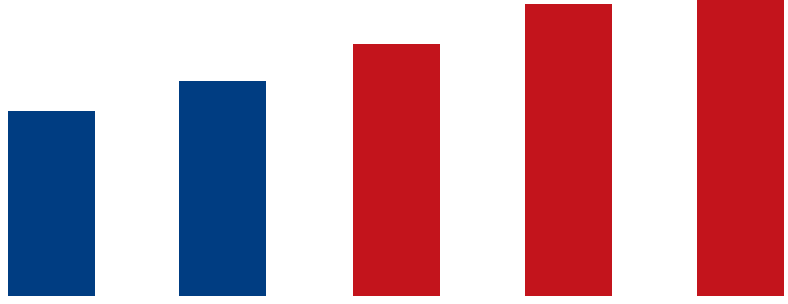


資料來源：兆豐國際投顧預估



OSATs' Revenue Composition Growth

TOP 10 OSATs Are All Customers of G2C+

4%  10%



ASE



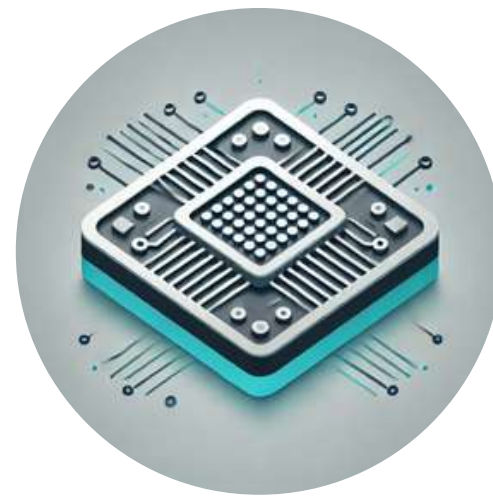
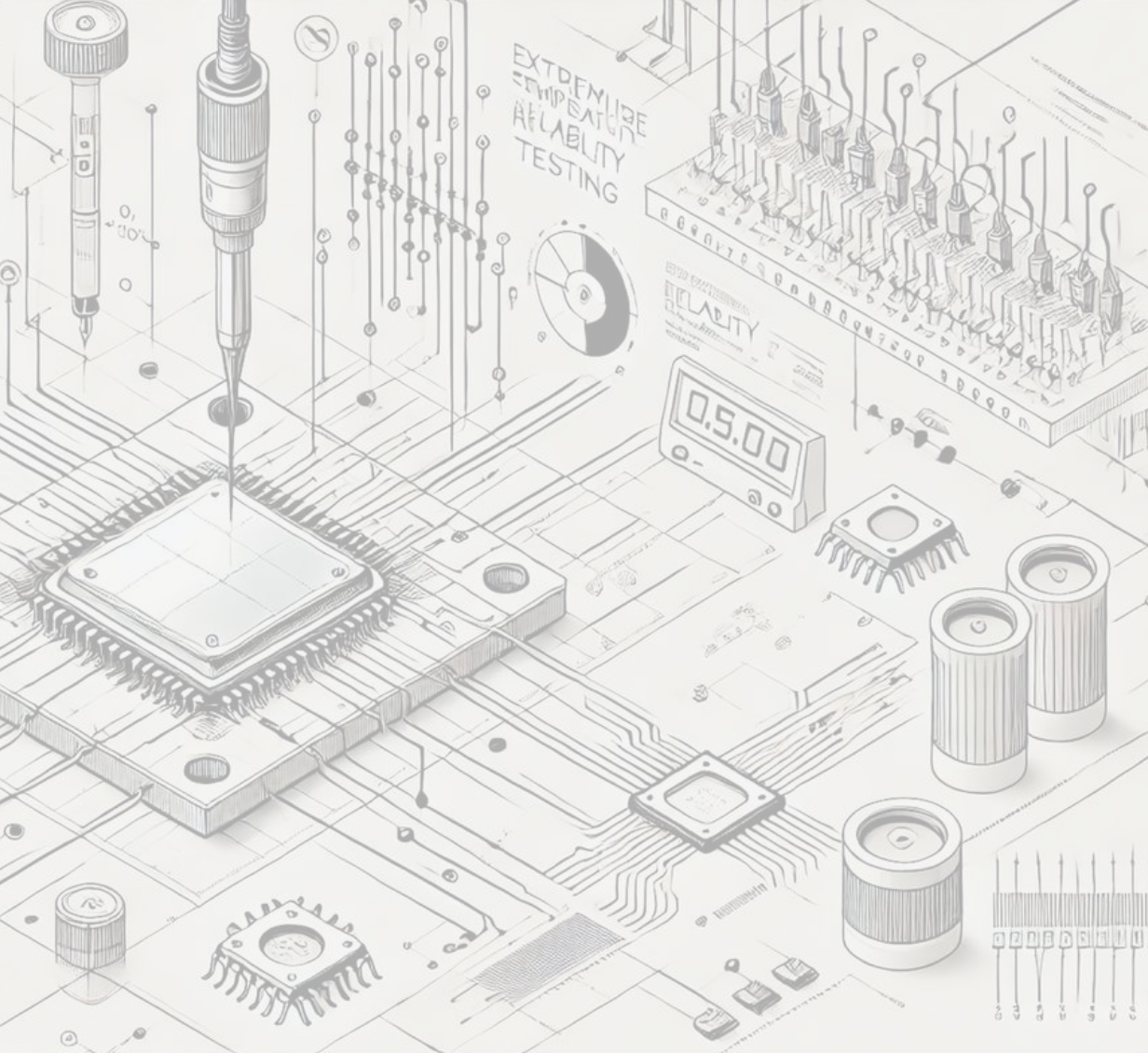
JCET

TF 通富微电



CHIPBOND
順邦科技

c sun 志聖



FoPLP Process and Dynamics

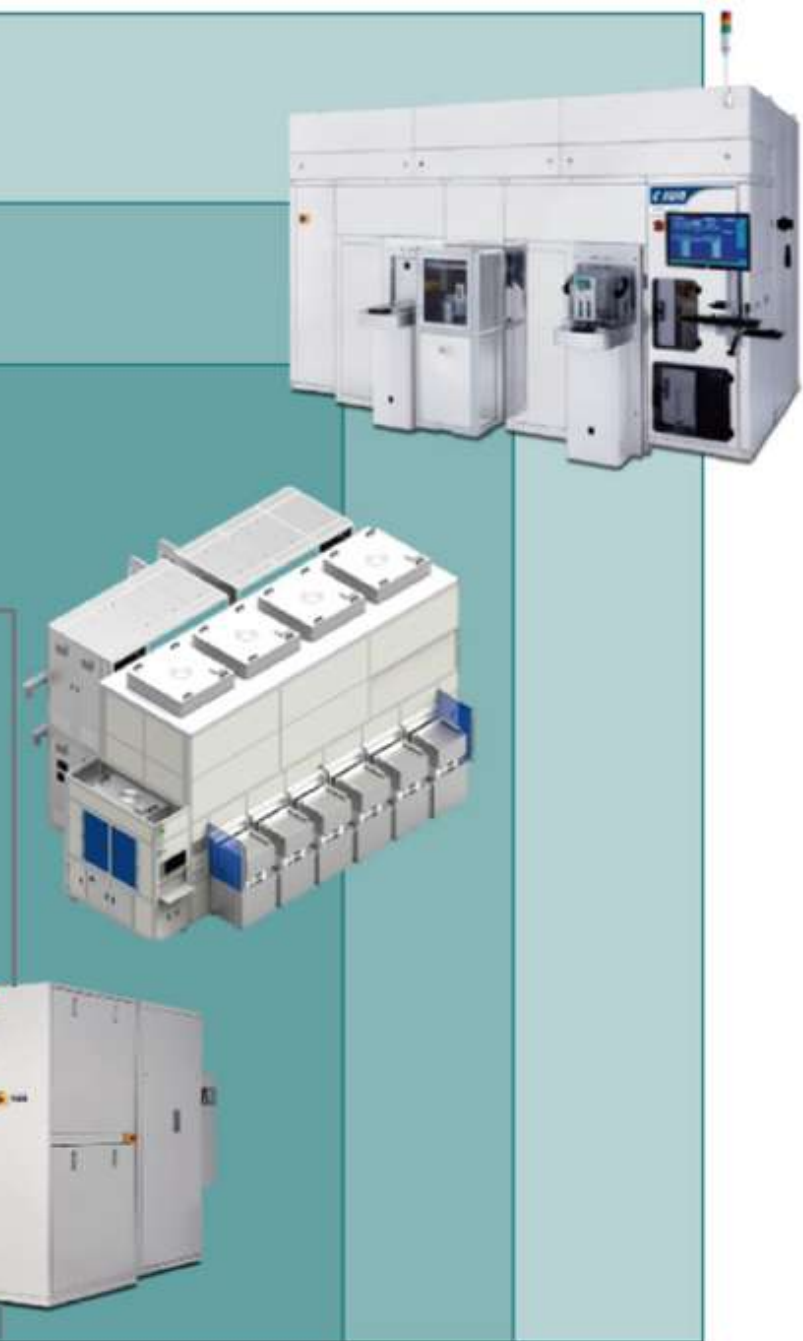
700 x 700

600 x 600

510 x 515

310 x 310

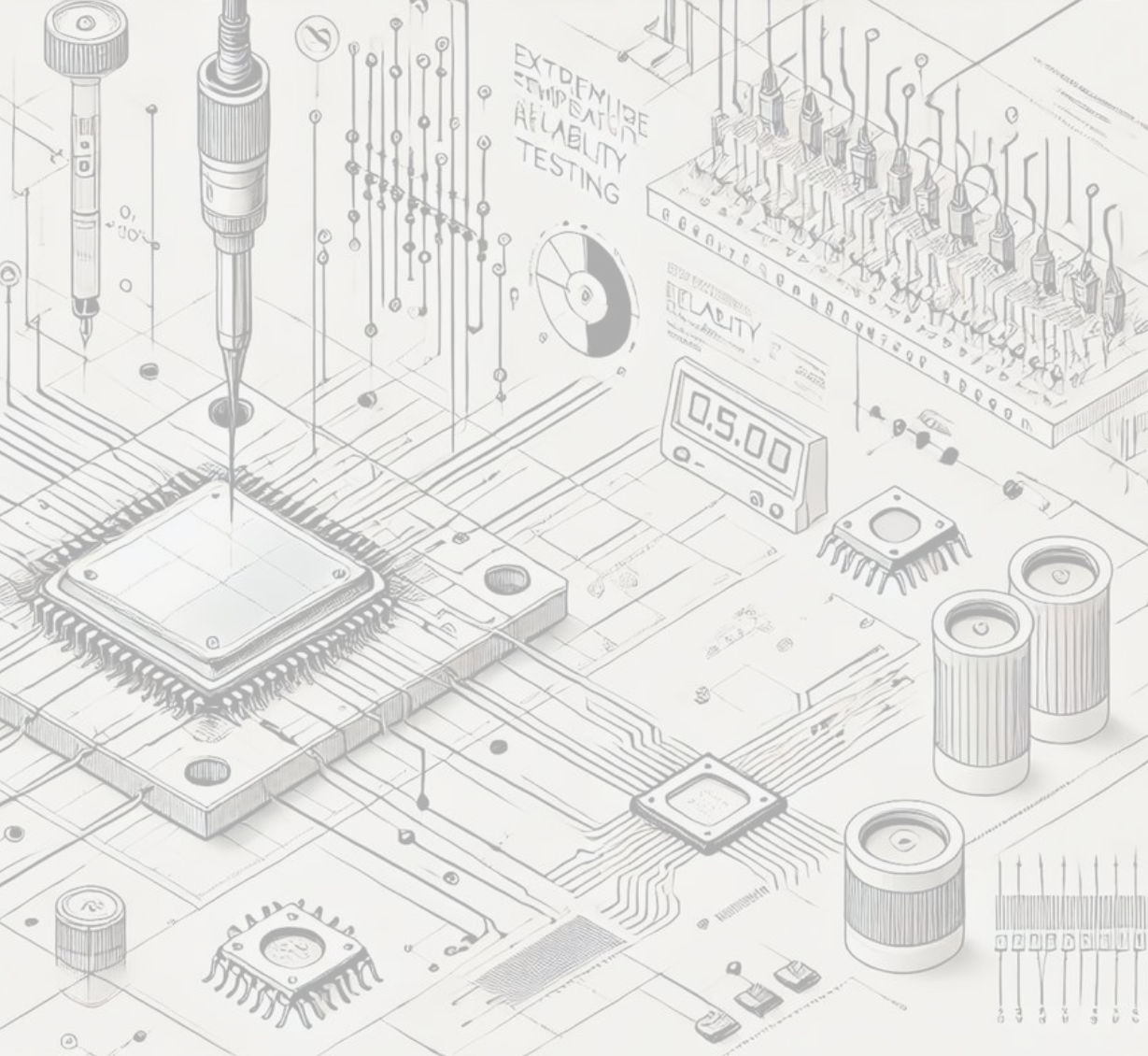
300 x 300



Prospects for
Equipment in Leading
Customers' Advanced
Packaging Processes

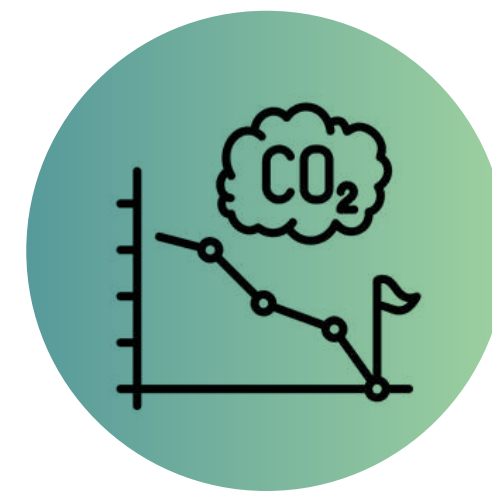
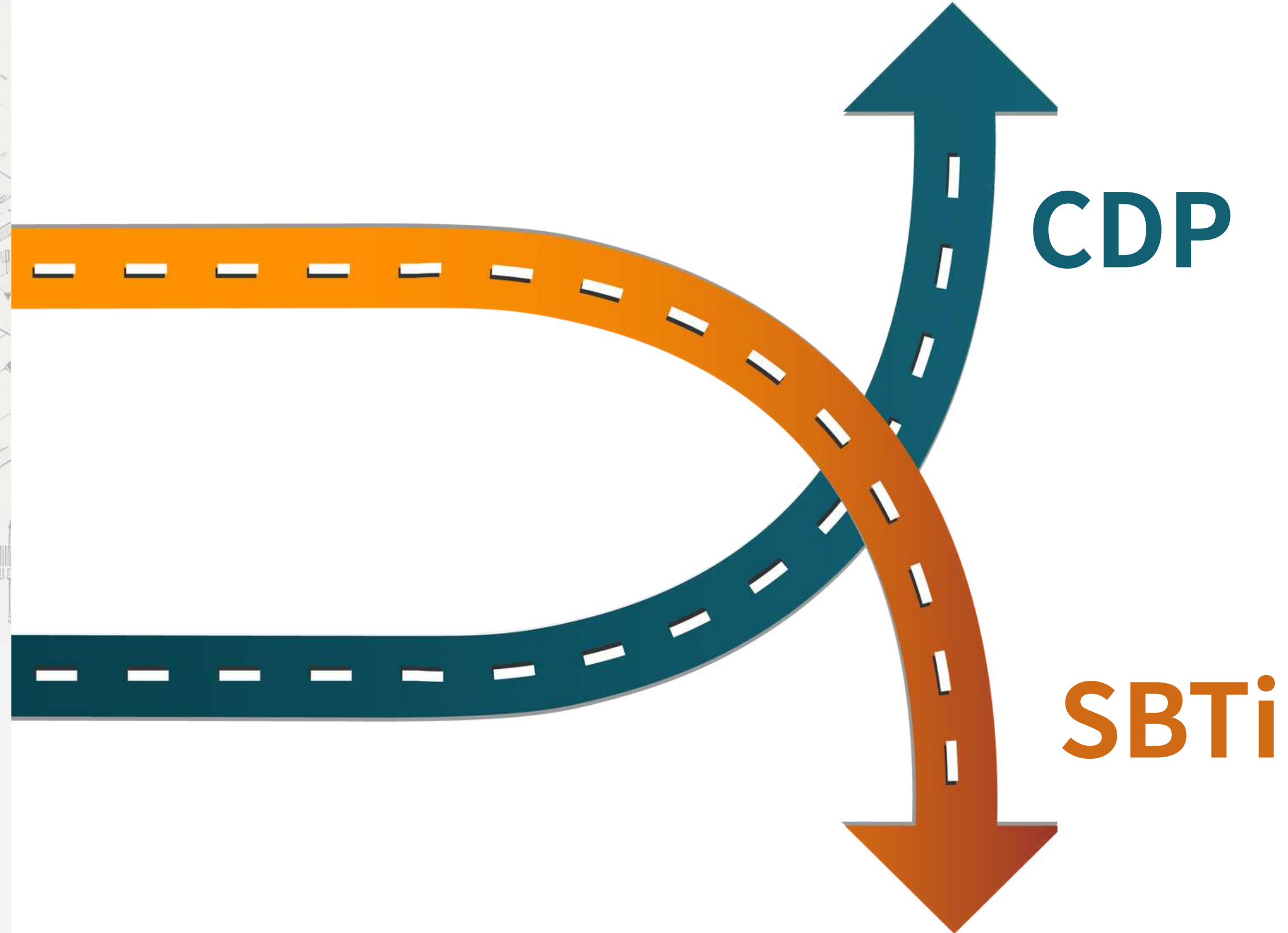
Internationalization (Grand Voyage)





Our commitment to
Sustainability and
Disclosure

Setting ISO 14067
Certification Targets



*c sun*志聖 Exhibition Preview

touch
TAIWAN 系列展
台北南港展覽館一館四樓

04/16-18, 2025

10:00~17:00

智慧顯示展 | 智慧製造展 | 電子生產製造設備展

敬邀您蒞臨攤位洽詢

4FM719

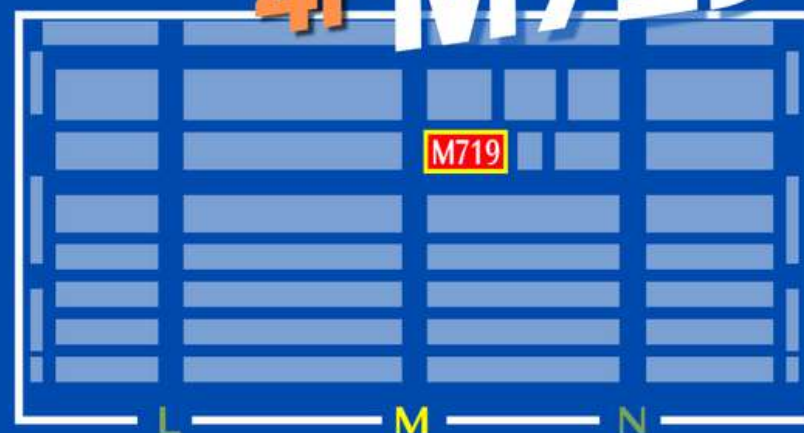
各界產業先進 您好

感謝您一直以來的鼓勵與愛護，

您的信賴與支持是我們成長茁壯的原動力。

誠摯地邀請您蒞臨4FM719攤位，

洽詢全方位智能化解決方案。



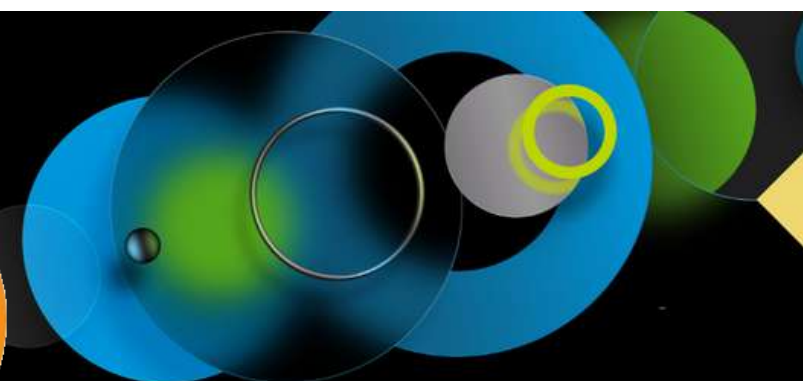
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GPM 均豪精密

GMM 均華精密

SEMICON[®] 30 YEARS
SOUTHEAST ASIA Special Edition
MAY 20-22, 2025 10:00~17:00 SGT
SANDS EXPO & CONVENTION CENTRE
SINGAPORE



BASEMENT 2
B1524

We sincerely invite you to visit our exhibition booth for inquiries.

Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

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GPM 均豪

GMM 均華



The background is a detailed technical illustration in a light orange/red hue. It features various electronic components and tools, including microchips, capacitors, resistors, and a circuit board. A digital display shows '0.5.00'. Text elements like 'EXTREME TEMPERATURE RELIABILITY TESTING' and 'RELIABILITY' are visible. The overall style is technical and precise.

Csun

A **G2C+** Alliance Company

Thank you for your attention
